

## Parker Chomerics CHO-BOND 584-29 Conductive Adhesive

Category : Polymer , Adhesive , Thermoset

### Material Notes:

Two-component, highly conductive adhesive system that combines the good adhesive characteristics of epoxy with the superior conductivity of silver. In addition to being available in bulk form, the material is offered in convenient premeasured "CHO-PAK" for rapid application. CHO-BOND® adhesive meets the most exacting electrical bonding requirements without the high temperatures, fluxes and expensive preparatory techniques usually needed to obtain effective lead-tin solder joints. Information provided by Chomerics

Order this product through the following link:

[http://www.lookpolymers.com/polymer\\_Parker-Chomerics-CHO-BOND-584-29-Conductive-Adhesive.php](http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-584-29-Conductive-Adhesive.php)

Physical Properties	Metric	English	Comments
Specific Gravity	2.30 - 2.70 g/cc	2.30 - 2.70 g/cc	
Thickness	25.4 microns	1.00 mil	Recommended

Mechanical Properties	Metric	English	Comments
Shear Strength	>= 8.27 MPa	>= 1200 psi	
	4.48 MPa	650 psi	
	@Treatment Temp. 21.0 °C, Time 86400 sec	@Treatment Temp. 69.8 °F, Time 24.0 hour	Lap
	6.21 MPa	900 psi	
	@Treatment Temp. 65.0 °C, Time 7200 sec	@Treatment Temp. 149 °F, Time 2.00 hour	Lap

Thermal Properties	Metric	English	Comments
CTE, linear	49.0 µm/m-°C	27.2 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Thermal Conductivity	1.20 - 1.50 W/m-K	8.33 - 10.4 BTU-in/hr-ft <sup>2</sup> -°F	
Maximum Service Temperature, Air	125 °C	257 °F	
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.0090 ohm-cm	<= 0.0090 ohm-cm	
	@Treatment Temp. 65.0 °C,	@Treatment Temp. 149 °F,	

Electrical Properties	Time 7200 sec Metric	Time 2.00 hour English	Comments
	<= 0.050 ohm-cm	<= 0.050 ohm-cm	
	@Treatment Temp. 21.0 °C, Time 86400 sec	@Treatment Temp. 69.8 °F, Time 24.0 hour	

Processing Properties	Metric	English	Comments
Cure Time	15.0 min	0.250 hour	
	@Temperature 113 °C	@Temperature 235 °F	
	1440 min	24.0 hour	
	@Temperature 24.0 °C	@Temperature 75.2 °F	
	1440 min	24.0 hour	
	@Temperature 24.0 °C	@Temperature 75.2 °F	
Pot Life	>= 30 min	>= 30 min	
Shelf Life	9.00 Month	9.00 Month	Bulk; From date of manufacture
	@Temperature 21.0 °C	@Temperature 69.8 °F	
	12.0 Month	12.0 Month	Bi-Paks; From date of manufacture
	@Temperature 21.0 °C	@Temperature 69.8 °F	

Descriptive Properties	Value	Comments
Binder	Epoxy	
Color	Silver/gray	
Consistency	Thin Paste	
Coverage	156.1 cm <sup>2</sup> /g	
Filler	Ag	
Mix Ratio	100:6.3	584 : Hardener
Working Life	0.5 hr	

## Contact Songhan Plastic Technology Co.,Ltd.

Website : [www.lookpolymers.com](http://www.lookpolymers.com)

Email : [sales@lookpolymers.com](mailto:sales@lookpolymers.com)

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215, Fengxian District, Shanghai City, China